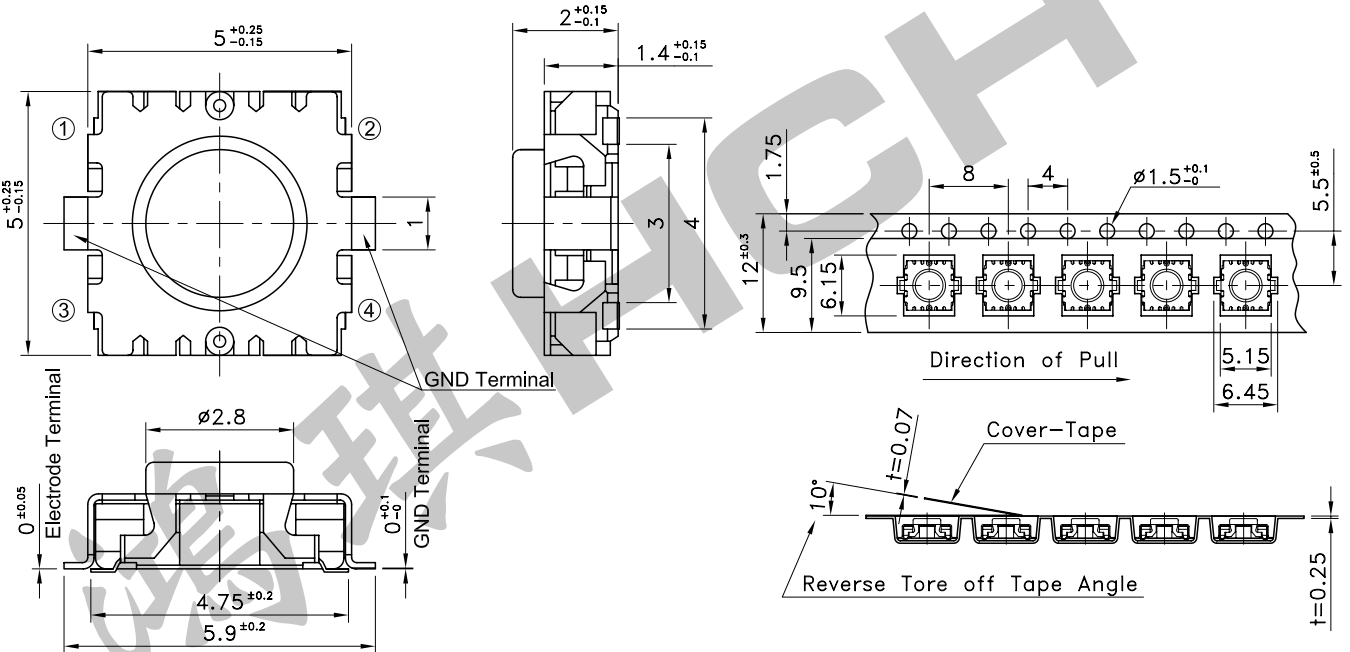
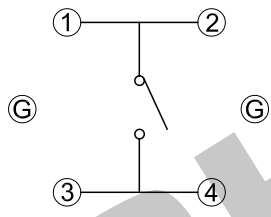
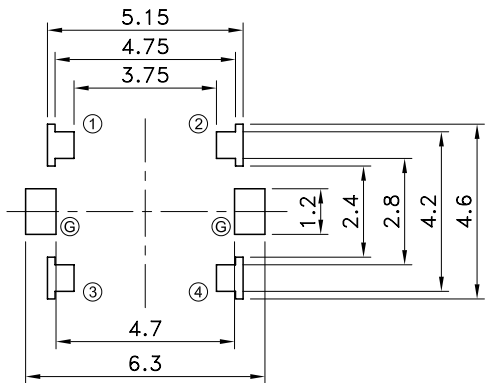


7	Cover	Stainless Steel	Sn Plated
6	Spacer	PolyAmide	With Glass
5	Stem	PolyAmide	With Glass
4	Contact	Stainless Steel	Ag-Clad 0.5μm
3	Cover Tape	Polyimide	t=25μm(Adhesive 25μm)
2	Terminal	Phosphor Bronze	Ag-Clad 0.5μm
1	Base	Polyphenylene Sulfide(PPS)	With Glass
No.	Parts	Material	Remarks

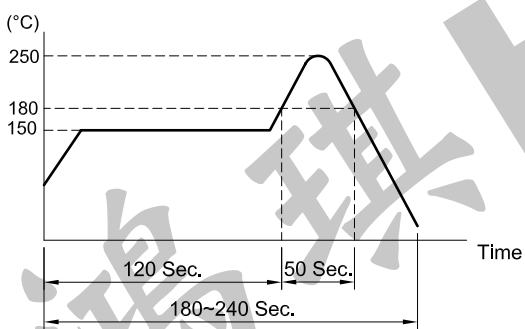


P.C.B TERMINAL POSITION

CIRCUIT ARRANGEMENT



REFLOW SOLDERING CONDITIONS



SPECIFICATIONS

- | | |
|--------------------------------|---|
| 1. Rating | :DC 15V 20mA |
| 2. Contact Resistance | :200mΩ Max. |
| 3. Insulation Resistance | :50MΩ Min. at DC 100V |
| 4. Dielectric Strength | :AC 100V for 1 minute |
| 5. Operating Force | :160±50gf |
| 6. Stroke | :0.18±0.1mm. |
| 7. Life | :500,000 Cycles |
| 8. Taping | :4,000 Pcs/Reel |
| 9. Operating Temperature Range | :-20~+70°C |
| 10. Reflow soldering | :According Reflow Profile
Max. 2 Times |

REVISION:		DATE:		REVISION:		DATE:	
UNIT:mm		THIRD ANGLE PROJECTION METHOD		TOL. UNLESS OTHERWISE STATED:±0.3		CODE NO.:HCH-793	
ISSUED		CONFIRMED		PART NO.		STS-083	
John		Joey		HCH® HORNG CHIH			
2000.10.08		2000.10.08		ISO9001 Certified ISO14001 Certified 鴻琪股份有限公司			